

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	188mΩ@10V	3A
	193mΩ@4.5V	

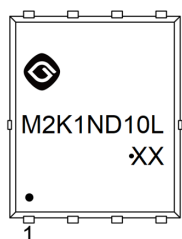
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance

Application

- Power Switching Application

MARKING:

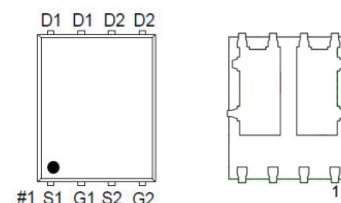


M2K1ND10L = Device Code

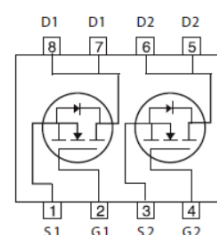
XX = Date Code

Solid Dot = Green Indicator

PDFN5×6-8L



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V _{DS}	100	V
Gate - Source Voltage		V _{GS}	±20	V
Continuous Drain Current ¹	T _C = 25℃	I _D	3	A
	T _C = 100℃	I _D	2.1	A
Pulsed Drain Current ²		I _{DM}	12	A
Power Dissipation ⁴	T _C = 25℃	P _D	6.9	W
Thermal Resistance from Junction to Ambient ⁵		R _{θJA}	60	℃/W
Thermal Resistance from Junction to Case		R _{θJC}	18	℃/W
Junction Temperature		T _J	150	℃
Storage Temperature		T _{STG}	-55~ +150	℃

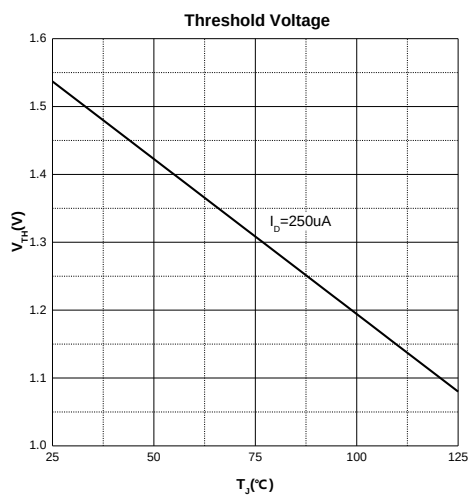
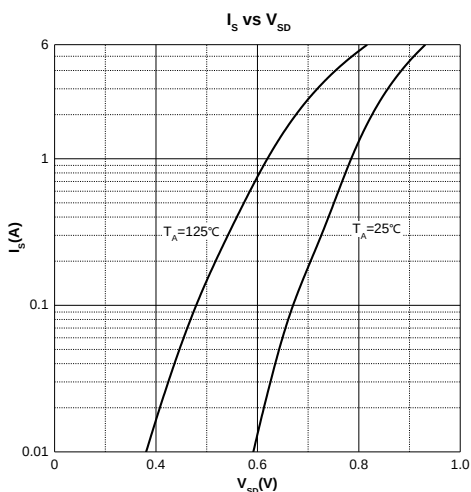
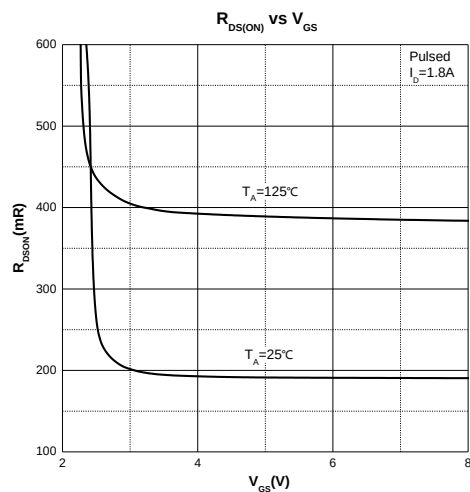
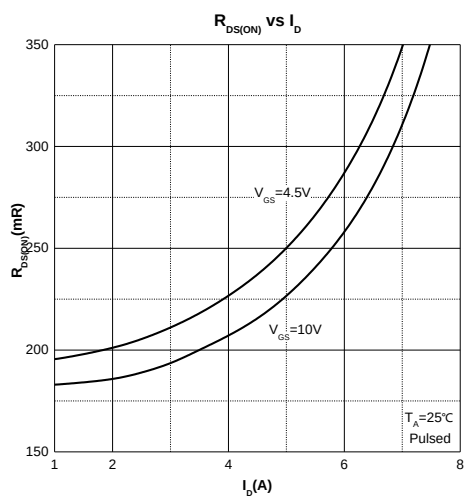
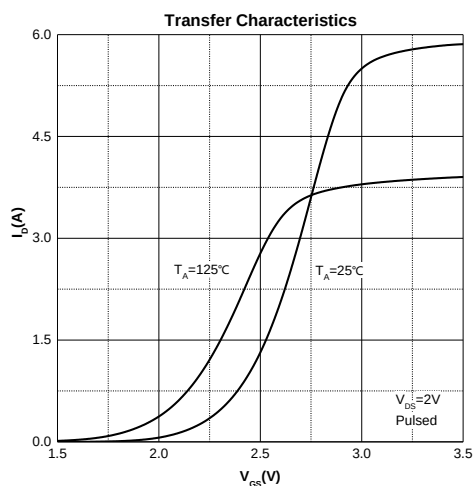
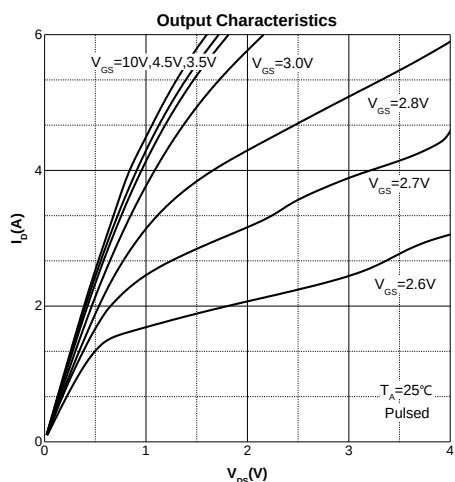
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

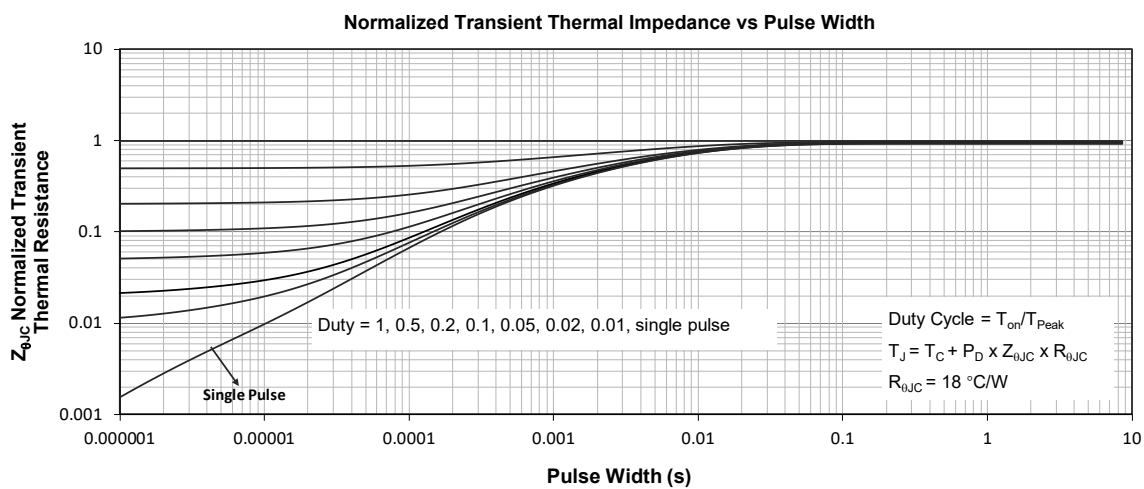
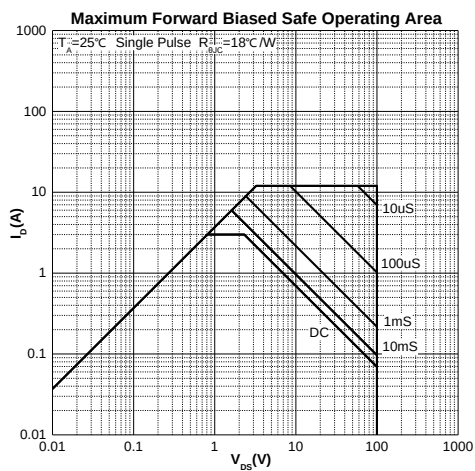
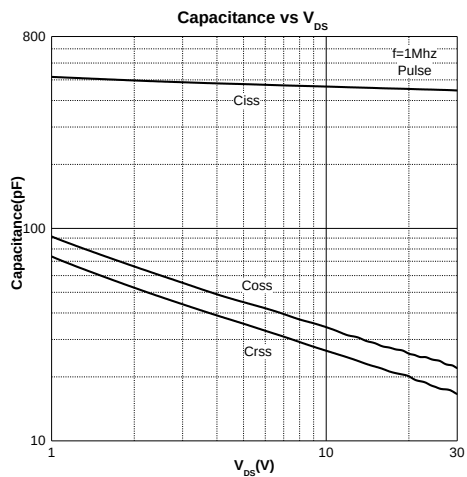
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80V, V _{GS} = 0V			1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics ³						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.5	2.5	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 2.0A		188	310	mΩ
		V _{GS} = 4.5V, I _D = 1.0A		193	320	
Forward Transconductance	g _{FS}	V _{DS} = 10V, I _D = 2A		4.3		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 45V, V _{GS} = 0V, f = 1MHz		450		pF
Output Capacitance	C _{oss}			17		
Reverse Transfer Capacitance	C _{rss}			9		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		1.96		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = 50V, V _{GS} = 10V, I _D = 2A		11.96		nC
Gate-source Charge	Q _{gs}			1.01		
Gate-drain Charge	Q _{gd}			2.83		
Turn-on Delay Time	t _{d(on)}	V _{DD} = 50V, V _{GS} = 10V, I _D = 2A R _G = 3Ω		13		ns
Turn-on Rise Time	t _r			52		
Turn-off Delay Ttime	t _{d(off)}			17		
Turn-off Fall Time	t _f			11		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = 1.5A			1.2	V

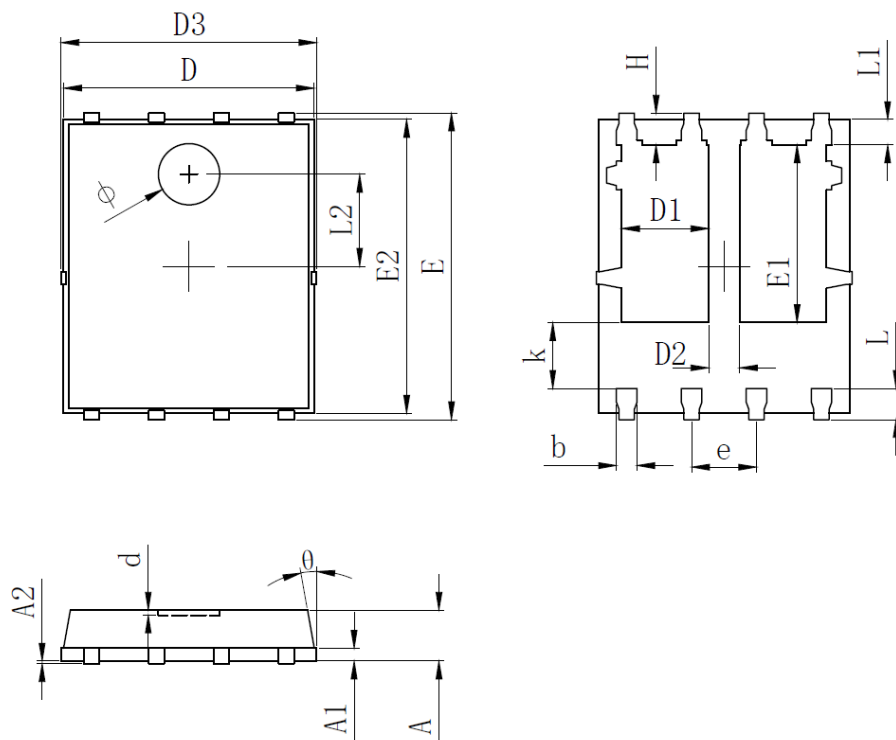
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 5.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics





PDFN5×6-8L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.254REF		0.010REF	
A2	0.000	0.050	0.000	0.002
D	4.824	4.976	0.190	0.196
D1	1.605	1.805	0.063	0.071
D2	0.500	0.700	0.020	0.028
D3	4.924	5.076	0.194	0.200
E	5.924	6.076	0.233	0.239
E1	3.375	3.575	0.133	0.141
E2	5.674	5.826	0.223	0.229
b	0.350	0.450	0.014	0.018
e	1.270TYP		0.050TYP	
L	0.534	0.686	0.021	0.027
L1	0.424	0.576	0.017	0.023
L2	1.800REF		0.071REF	
k	1.190	1.390	0.047	0.055
H	0.549	0.701	0.022	0.028
θ	8°	12°	8°	12°
Φ	1.100	1.300	0.043	0.051
d	-	0.100	-	0.004